OPALE V2 Compact

SWap-C, trusted and flexible



■ Ready for OEM with Modified COTS services

As processing performance continues to improve, ECRIN Systems is dedicated to minimize the SWaP-C envelope of OPALE V2 series. High-end computing performance in a 2U chassis with a depth under 20" (492mm), OPALE V2 Compact fits most any 19" rack mount space. It will be particularly useful when foot print, performance, reliability and longevity are not optional: military shelter base station, rugged servers for harsh environments, simulator, telemetry, telecom, medical imaging, infotainment, control/command station, test bench system, Internet appliance...

Distinctively customized oriented thanks to our in-house design center, ECRIN Systems will help to personalize your computer and give you competitive advantage in the industrial world.

To precisely meet your requirements, even for small quantities, ECRIN takes full system development responsibility and guarantee long term availability to allow you to concentrate on your added value. From mechanical parts to industrial design, with front and remote user interfaces, user LED's and I/O's, easy customized front and rear connectors, specific face-plate color and design, Lexan polycarbonate sheet with your logo and brand name, we will offer you a unique look that will shape your image and promote your sales.

Drop shipping is available to facilitate a rapid, more convenient deployment directly to your end customers.

- > Modified COTS with easy brand naming, configuration and customization for competition advantage
- > Security with trusted boot
- > Local and remote active management to detect errors before they occur
- > Enhanced asset protection for continuous operation:
- Durable connectors: 15 microinch Gold/Metal plated connectors assure long term reliability
- Enhanced USB compatibility: USB power supply ensures stability (5V +/-5%)
- Rugged EMI construction: EN55032 Class B Radiation test, -10dB than competition Class A
- > MIL-STD tests passed (for T°C, shocks & vibrations, humidity, noise)
- > Efficient thermal concept to get higher MTBF
- > Reduced TCO with reporting log file and downtime in harsh environments
- > Energy efficient design / Low noise
- > Long life management: up to 10 years with revision control
- > Advanced Multi-Core "Skylake" boosted computing performance with DDR4 speeds and timings
- > Expandability with 4 full-height and full-length I/O cards into PICMG 1.3 butherfly backplane



E: 4x tri-color LEDs F: 2x USB G: 3.5" drive bay H: 5.25" drive bay

> 4x COM 2x USB3.0 PS/2 KB&MS

2x RJ45

Rack specifications		
Construction	Anti-corrosion and long term heavy-duty steel	A B C D E
Dimensions (W x H x D)	19" / 2U with 19.4 inch depth (483x88x492mm)	
Weight	12.5 kg (standard configuration)	
Color	Black	
Cooling	Three 80mm ball bearing low noise fans with monitoring	
	Top access for easy maintenance, cover removed	
Power supply	2U form factor, compliant with Mini Redundant PSU	F
Drive bays	One 5.25" front accessible drive bay or Slim CD + 3.5"drive bay	
	One 3.5" front accessible drive bay	· · · · · · · · · · · · · · · · · · ·
Backplane configuration	5 slots, 2U butterfly form factor backplane. Full length board on every slot	
Front panel	Front door for drive bays and USB access	
	Embedded MMI, 4 LEDs with I/O capabilities	
	Lexan for easy customization	A: Single door with 2x Thumbscrews
Cards lock	Retaining bracket for cards	B: LCD 2x16 characters F
	Rugged front holding parts for full length boards (SHB & I/O cards)	C: Keyboard (Power & Reset) D: Lexan for easy customization
Packaging (W x H x D)	580x260x680mm	b. Lexuit for easy custoffization
SHB specifications		
· · · · · · · · · · · · · · · · · · ·		
Form factor	PICMG 1.3 - Graphic Class / Server Class - PCI Express Gen 3	
· · · · · · · · · · · · · · · · · · ·	PICMG 1.3 - Graphic Class / Server Class - PCI Express Gen 3 LGA1151 socket - 6 th Gen Intel [®] Core [™] processor (codename Skylake)	
Form factor		
Form factor Processor	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake)	
Form factor Processor Chipset	LGA1151 socket - 6 th Gen Intel [®] Core [™] processor (codename Skylake) Intel [®] Q170 Express chipset supporting PCI Express 3.0	- 4x SATA
Form factor Processor Chipset Memory	LGA1151 socket - 6 th Gen Intel [®] Core [™] processor (codename Skylake) Intel [®] Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM)	4x SATA
Form factor Processor Chipset Memory Video	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal)	4x SATA Duai DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory	
Form factor Processor Chipset Memory Video BIOS	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® 0170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® 0170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option)	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® 0170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane)	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® 0170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer Hardware monitor	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® 0170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset CPU & System temperature, fan speed and onboard DC voltages	Dual DDR4 DIMMS DVI-D
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer Hardware monitor Manageability	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset CPU & System temperature, fan speed and onboard DC voltages SEMA support with BMC, SEMA cloud	Dual DDR4 DIMMs DVI-D 6x USB3.0
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer Hardware monitor Manageability SSI Trusted boot	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset CPU & System temperature, fan speed and onboard DC voltages SEMA support with BMC, SEMA cloud 1x box header for TPM module (optional) - Atmel AT97SC3204 TIS 1.2	Dual DDR4 DIMMs DVI-D 6x USB3.0 LGA 1151 socket Intel® 0170 TPM
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer Hardware monitor Manageability	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset CPU & System temperature, fan speed and onboard DC voltages SEMA support with BMC, SEMA cloud 1x box header for TPM module (optional) - Atmel AT97SC3204 TIS 1.2 Serial port : 2x RS-232, 2x RS-232/422/485	Dual DDR4 DIMMs DVI-D 6x USB3.0
Form factor Processor Chipset Memory Video BIOS Ethernet Disk Audio Codec USB Watchdog timer Hardware monitor Manageability SSI Trusted boot	LGA1151 socket - 6 th Gen Intel® Core™ processor (codename Skylake) Intel® Q170 Express chipset supporting PCI Express 3.0 Dual-channel DDR4-2133 up to 32 GB (2* DIMM) Integrated Intel® HD Graphics (VGA and DVI-D internal) AMI® UEFI BIOS; 128 Mbit SPI Flash Memory 2 x GbE (Intel® 1219LM + Intel® 1211-AT) Intel® AMT and Wake On LAN support 4x SATA 6Gb/s ports Intel® Rapid Storage Technology, supports RAID 0/1/5/10 High definition audio interface with DB-Audio2 (option) 8x USB 3.0, 4x USB 2.0 (on backplane) 24~65535 sec software programmable, can generate system reset CPU & System temperature, fan speed and onboard DC voltages SEMA support with BMC, SEMA cloud 1x box header for TPM module (optional) - Atmel AT97SC3204 TIS 1.2	Dual DDR4 DIMMs DVI-D 6x USB3.0 LGA 1151 socket Intel® 0170 TPM

Duckplane specifications				
EBP-D5E2	1xSHB / 1xPCIe x16 Gen3 / 1xPCIe x4 Gen3 / 2xPCI 4x USB 2.0	The Control of the Co	The same of	
C100192-A C100192-B	1x SHB / 2xPCIe x8 Gen3 / 1xPCIe x4 - 2x SATA, 2x USB 2.0 1x SHB / 1xPCIe x8 Gen3 / 3xPCIe x4 - 2x SATA, 2x USB 2.0			
BPC8219	1xSHB / 3xPCle x16 Gen3 / 1xPCle x4 Gen3 4x USB 2.0			
Environmental specifications				
Temperature	Operating: 0~50°C (MIL STD 810 G method 502 5 / 501 5) - Storage: -20~80°C			

Temperature	Operating: 0~50°C (MIL STD 810 G, method 502.5 / 501.5) - Storage: -20~80°C	
Humidity	Operating: 5% to 90% non condensing	
Altitude	0-3000m (0-10.000ft) operating	
Shock & vibration	Operating: 15G, 11ms 6 axis (MIL STD 810 G, method. 516.6) - 5~100 Hz 0.8G (MIL STD 810 G, method. 514.5) 34.9 dBA (Iddle), 35.9 dBA (50%), 42 dBA (80%) - MIL-STD-740-1	
Noise		
CE certification	EMC: 2014/30/UE; EN 61000-6-2, EN55032, EN 55024 - SAFETY: 2014/35/UE; EN60950-1: 2006 2nd edition A11: 2009 + A1: 2010 + A12: 2011 + A2: 2014	

> Branding user's Lexan - Costless, NRE fees only

> Modified COTS customization:

- System & network information - Watchdog & elapsed time count		mation Log file	- Front panel design - Specific I/O on front panel / special connectors on rear panel - Specific H/W configurations		
- Redundant P/S default		- Easy configuration with .TXT file	- Specific S/W functi	onality Call us for more information	
Standard configuration		Options			
	Power Supply Unit	ATX 12V - 400W - High Efficiency 80+ 90 ~ 240 VAC full range / 47~63 Hz 5V@22A, 12V@32A, -12V@0.8A, 3.3V@22A, 5Vstb@3.5A Option for 2x 420W mini-Redundant 2U P/S High Efficiency (80+), 90-240VAC auto range /47-63Hz	Processor	- Intel® Core™ i7-6700 (4C/8T, 3.4 GHz, 8M Cache, 14nm, 65W TDP) - Intel® Core™ i7-6700TE (4C/8T, 2.4 GHz 8M Cache, 14nm, 35W TDP) - Intel® Core™ i5-6500 (4C/4T, 3.2 GHz, 6M Cache, 14nm, 65W TDP) - Intel® Core™ i5-6500TE (4C/4T, 2.3 GHz, 6M Cache, 14nm, 35W TDP) - Intel® Core™ i5-6100 (2C/4T, 3.7 GHz, 3M Cache, 14nm, 51W TDP)	
	Back plane	EBP-D5E2 in standard configuration		- Intel® Core™ i3-6100TE (2C/4T, 2.7 GHz, 4M Cache, 14nm, 35W TDP)	
Drives 1 x Slim DVDRW		Memory	DDR4-2133 : 4Go / 8Go / 16Go / 32Go		

Disk

0\$

sales@ecrin.com

Front I/O (behind door)

Rear I/0

Headquarters

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> Intel® AMT for remote management

> Local control with embedded MMI (Windows & Linux services)

1 x 2.5" SATA Removable Drive

2 x USB 2.0

 $1\,x\,3.5^{\prime\prime}$ front accessible drive bay free

VGA + 2xGbE + 4xUSB 3.0 + 2xCOM

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Marketing & sales

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Microsoft® Windows® 7 32/64-bit, Windows 8.1 & 10 64-bit - Linux 32/64-bit

- 2.5" 7200 RPM Hard Drive (500Go ~ 1To)

- SLC and/or MLC Solid State Drive (32 Go ~ 2To)

- Up to 4x hot swap 2.5" HD/SSD with optional 4in1 drive bay